

	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	95	"5588861" "5126822" "6149449" "6347946" "5672981" "5859538" "6371782" "5880590" "6345999"	USPAT	2004/02/23 03:15
2	BRS	9	5588861.pn. 5126822.pn. 6149449.pn. 6347946.pn. 5672981.pn. 5859538.pn. 6371782.pn. 5880590.pn. 6345999.pn.	USPAT	2004/02/23 03:18
3	BRS	55	257/797 and alignment\$3 near (ball or pad or contact or terminal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 03:32
4	BRS	0	(semiconductor or die or chip or IC) and alignment\$3 near (ball or pad or contact or terminal) same plexer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 03:40
5	BRS	0	(semiconductor or die or chip or IC) and alignment\$3 near (ball or pad or contact or terminal) same multiplexer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 03:40
6	BRS	0	(semiconductor or die or chip or IC) and alignment\$3 near (ball or pad or contact or terminal) same multiplex\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 03:41
7	BRS	0	(semiconductor or die or chip or IC) and alignment\$3 near (ball or pad or contact or terminal) same (multiplex\$3 or plex\$3 or MUX)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 03:41

	Type	Hits	Search Text	DBs	Time Stamp
8	BRS	49	(semiconductor or die or chip or IC) and alignment\$3 near (ball or pad or contact or terminal) same (divid\$3 or split\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 03:42
9	BRS	20	(semiconductor or die or chip or IC) and alignment\$3 near (ball or pad or contact or terminal) with (divid\$3 or split\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 03:47
10	BRS	41	(semiconductor or die or chip or IC) and alignment\$3 near (ball or pad or contact or terminal) with (divid\$3 or split\$3 or switch)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 03:47
11	BRS	21	((semiconductor or die or chip or IC) and alignment\$3 near (ball or pad or contact or terminal) with (divid\$3 or split\$3 or switch)) not ((semiconductor or die or chip or IC) and alignment\$3 near (ball or pad or contact or terminal) with (divid\$3 or split\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 04:18
12	BRS	32008	(semiconductor or die or chip or IC) and (BGA or array) and alignment and (multiplex\$3 or plex\$3 or divid\$3 or split\$3 or mux or switch\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 04:28
13	BRS	8211	(semiconductor or die or chip or IC) and (BGA or array) and alignment and (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 04:28

	Type	Hits	Search Text	DBs	Time Stamp
14	BRS	1856	(semiconductor or die or chip or IC) and (BGA or array) same alignment and (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 04:28
15	BRS	201	(semiconductor or die or chip or IC) and (BGA or array) same alignment same (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 04:29
16	BRS	133	(semiconductor or die or chip or IC) and (BGA or array) same alignment same (multiplex\$3 or plex\$3 or mux)	USPAT; JPO	2004/02/23 04:37
17	BRS	11	(semiconductor or die or chip or IC) and (BGA or array) and alignment with (solder or pad or contact or terminal) same (multiplex\$3 or plex\$3 or mux)	USPAT; JPO	2004/02/23 04:50
18	BRS	0	438/5 and (semiconductor or die or chip or IC) and (BGA or array) and alignment same (solder or pad or contact or terminal) same (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 04:51
19	BRS	0	438/6 and (semiconductor or die or chip or IC) and (BGA or array) and alignment same (solder or pad or contact or terminal) same (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 04:51

	Type	Hits	Search Text	DBs	Time Stamp
20	BRS	0	438/7 and (semiconductor or die or chip or IC) and (BGA or array) and alignment same (solder or pad or contact or terminal) same (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 04:51
21	BRS	0	438/5 and (semiconductor or die or chip or IC) and (BGA or array) and alignment and (solder or pad or contact or terminal) same (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 04:51
22	BRS	0	438/5 and (semiconductor or die or chip or IC) and (BGA or array) and alignment and (solder or pad or contact or terminal) and (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 04:51
23	BRS	4	438/6 and (semiconductor or die or chip or IC) and (BGA or array) and alignment and (solder or pad or contact or terminal) and (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 04:52
24	BRS	1	438/7 and (semiconductor or die or chip or IC) and (BGA or array) and alignment and (solder or pad or contact or terminal) and (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 04:53

	Type	Hits	Search Text	DBs	Time Stamp
25	BRS	1	438/8 and (semiconductor or die or chip or IC) and (BGA or array) and alignment and (solder or pad or contact or terminal) and (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 04:53
26	BRS	1	438/9 and (semiconductor or die or chip or IC) and (BGA or array) and alignment and (solder or pad or contact or terminal) and (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 04:53
27	BRS	3	438/10 and (semiconductor or die or chip or IC) and (BGA or array) and alignment and (solder or pad or contact or terminal) and (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 05:15
28	BRS	2	438/11 and (semiconductor or die or chip or IC) and (BGA or array) and alignment and (solder or pad or contact or terminal) and (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 05:16
29	BRS	2	438/12 and (semiconductor or die or chip or IC) and (BGA or array) and alignment and (solder or pad or contact or terminal) and (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 05:16

	Type	Hits	Search Text	DBs	Time Stamp
30	BRS	0	438/13 and (semiconductor or die or chip or IC) and (BGA or array) and alignment and (solder or pad or contact or terminal) and (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 05:16
31	BRS	14	438/14 and (semiconductor or die or chip or IC) and (BGA or array) and alignment and (solder or pad or contact or terminal) and (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 05:24
32	BRS	12	438/15 and (semiconductor or die or chip or IC) and (BGA or array) and alignment and (solder or pad or contact or terminal) and (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 05:26
33	BRS	6	438/16 and (semiconductor or die or chip or IC) and (BGA or array) and alignment and (solder or pad or contact or terminal) and (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 05:26
34	BRS	14	438/17 and (semiconductor or die or chip or IC) and (BGA or array) and alignment and (solder or pad or contact or terminal) and (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 05:29

	Type	Hits	Search Text	DBs	Time Stamp
35	BRS	12	438/18 and (semiconductor or die or chip or IC) and (BGA or array) and alignment and (solder or pad or contact or terminal) and (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 05:29
36	BRS	0	438/597 and (semiconductor or die or chip or IC) and (BGA or array) and alignment and (solder or pad or contact or terminal) and (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 05:29
37	BRS	4	438/598 and (semiconductor or die or chip or IC) and (BGA or array) and alignment and (solder or pad or contact or terminal) and (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 05:30
38	BRS	4	438/599 and (semiconductor or die or chip or IC) and (BGA or array) and alignment and (solder or pad or contact or terminal) and (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 05:30
39	BRS	4	438/612 and (semiconductor or die or chip or IC) and (BGA or array) and alignment and (solder or pad or contact or terminal) and (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 05:31

	Type	Hits	Search Text	DBs	Time Stamp
40	BRS	3	438/613 and (semiconductor or die or chip or IC) and (BGA or array) and alignment and (solder or pad or contact or terminal) and (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 05:31
41	BRS	1	"6466047".PN.	USPAT	2004/02/23 05:34
42	BRS	1	"6433574".PN.	USPAT	2004/02/23 05:34
43	BRS	1	"6366112".PN.	USPAT	2004/02/23 06:05
44	BRS	44814	(board) and orientation	USPAT	2004/02/23 13:20
45	BRS	14	(board) with four near orientation	USPAT	2004/02/23 13:20
46	BRS	22	(semiconductor or die or chip or IC) and (BGA or array) same alignment same (multiplex\$3 or plex\$3 or mux) and orientation	USPAT	2004/02/23 13:27
47	BRS	0	(semiconductor or die or chip or IC) and (BGA or array) same alignment same (multiplex\$3 or plex\$3 or mux) and orientation near four	USPAT	2004/02/23 13:28
48	BRS	2	(semiconductor or die or chip or IC) and (BGA or array) same (multiplex\$3 or plex\$3 or mux) and orientation near four	USPAT	2004/02/23 13:30
49	BRS	0	(semiconductor or die or chip or IC) and (BGA) same (multiplex\$3 or plex\$3 or mux) and orientation with four and orientation with (multiplex\$3 or plex\$3 or mux)	USPAT	2004/02/23 13:31

	Type	Hits	Search Text	DBs	Time Stamp
50	BRS	5	(semiconductor or die or chip or IC) and (BGA or (ball or pin) nearer array) same (multiplex\$3 or plex\$3 or mux) and orientation with four and orientation with (multiplex\$3 or plex\$3 or mux)	USPAT	2004/02/23 13:38
51	BRS	5	(semiconductor or die or chip or IC) and (PGA or BGA or (ball or pin) nearer array) same (multiplex\$3 or plex\$3 or mux) and orientation with four and orientation with (multiplex\$3 or plex\$3 or mux)	USPAT	2004/02/23 13:39
52	BRS	5	(semiconductor or die or chip or IC) and (PGA or BGA or (ball or pin) nearer array) same (multiplex\$3 or plex\$3 or mux) and orientation with four and orientation with (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 13:41
53	BRS	3	(semiconductor or die or chip or IC) and (PGA or BGA or ball or pin) same (multiplex\$3 or plex\$3 or mux) and orientation with four and orientation with (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 13:58

	Type	Hits	Search Text	DBs	Time Stamp
54	BRS	8	(semiconductor or die or chip or IC) and (PGA or BGA or ball or pin) same (multiplex\$3 or plex\$3 or mux) and orientation with four	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 13:59
55	BRS	3	(semiconductor or die or chip or IC) with us\$3 with orientation and (PGA or BGA or ball or pin) same (multiplex\$3 or plex\$3 or mux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 14:00
56	BRS	1	"6548907"	USPAT	2004/02/23 14:21
57	BRS	1	6331450.pn.	USPAT	2004/02/24 19:02
58	BRS	1	6233540.pn.	USPAT	2004/02/24 19:03
59	BRS	959	29/837	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/27 14:40
60	BRS	161	29/837 and orientat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/27 18:23
61	BRS	2	6233540.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/27 18:23
62	BRS	1	6233540.pn. and "C++"	USPAT	2004/02/27 18:24
63	BRS	499	29/832 and orientat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/03 19:48
64	BRS	136	29/854 and orientat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/03 19:48

	Type	Hits	Search Text	DBs	Time Stamp
65	BRS	172	29/884 and orientat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/05 23:38
66	BRS	91	29/876 and orientat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/06 00:02
67	BRS	215	29/593 and orientat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/06 00:02
68	BRS	153	257/780 and orientat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/08 09:03
69	BRS	428	257/778 and orientat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/08 09:25
70	BRS	236	257/786 and orientat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/08 09:25